2N3634, 2N3634L, 2N3635, 2N3635L, 2N3636, 2N3636L, 2N3637, 2N3637L

Low Power Transistors

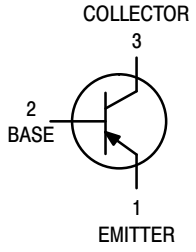
PNP Silicon

ON Semiconductor®

http://onsemi.com

Features

- MIL−PRF−19500/357 Qualified
- Available as JAN, JANTX, JANTXV and JANHC



MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	2N3634/L 2N3635/L	2N3636/L 2N3637/L	Unit
Collector − Emitter Voltage	V_{CEO}	−140	−175	Vdc
Collector − Base Voltage	V_{CBO}	−140	−175	Vdc
Emitter − Base Voltage	V_{EBO}	−5.0		Vdc
Collector Current − Continuous	I_C	1.0		Adc
Total Device Dissipation @ T_A = 25°C	P_T	1.0		W
Total Device Dissipation @ T_C = 25°C	P_T	5.0		W
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +200		°C

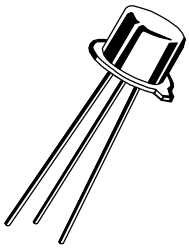
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	175	°C/W
Thermal Resistance, Junction to Case	$R_{\theta JC}$	35	°C/W

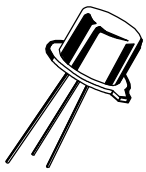
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ORDERING INFORMATION

Level	Device	Package	Shipping
JAN JANTX JANTXV JANHC	2N3634	TO−39	Bulk
	2N3635		
	2N3636		
	2N3637		
	2N3634L	TO−5	Bulk
	2N3635L		
	2N3636L		
	2N3637L		



TO−5
CASE 205AA
STYLE 1
2N3634L
2N3635L
2N3636L
2N3637L



TO−39
CASE 205AB
STYLE 1
2N3634
2N3635
2N3636
2N3637

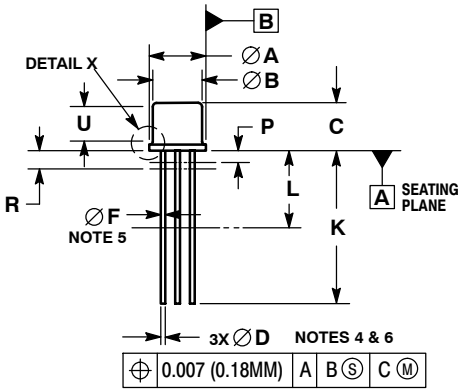
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

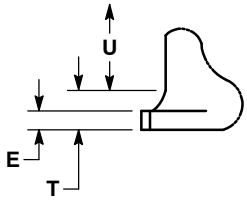
Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector−Emitter Breakdown Voltage (I_C = −10 mA)	2N3634, 2N3635 2N3636, 2N3637	$V_{(BR)CEO}$	 −140 −175	 − −	V
Emitter−Base Cutoff Current (V_{EB} = −3.0 V) (V_{EB} = −5.0 V)		I_{EBO}	 − −	 −50 −10	 nA μA
Collector−Emitter Cutoff Current (V_{CE} = −100 V)		I_{CEO}	 −	 −10	 μA
Collector−Base Cutoff Current (V_{CB} = −100 V) (V_{CB} = −140 V) (V_{CB} = −175 V)	 2N3634, 2N3635 2N3636, 2N3637	I_{CBO}	 − − −	 −100 −10 −10	 nA μA μA
ON CHARACTERISTICS (Note 1)					
DC Current Gain (I_C = −0.1 mA, V_{CE} = −10 V) (I_C = −1.0 mA, V_{CE} = −10 V) (I_C = −10 mA, V_{CE} = −10 V) (I_C = −50 mA, V_{CE} = −10 V) (I_C = −150 mA, V_{CE} = −10 V)	2N3634, 2N3636	h_{FE}	 25 45 50 50 30	 − − − 150 −	−
DC Current Gain (I_C = −0.1 mA, V_{CE} = −10 V) (I_C = −1.0 mA, V_{CE} = −10 V) (I_C = −10 mA, V_{CE} = −10 V) (I_C = −50 mA, V_{CE} = −10 V) (I_C = −150 mA, V_{CE} = −10 V)	2N3635, 2N3637	h_{FE}	 55 90 100 100 60	 − − − 300 −	−
Collector−Emitter Saturation Voltage (I_C = −10 mA, I_B = −1.0 mA) (I_C = −50 mA, I_B = −5.0 mA)		$V_{CE(sat)}$	 − −	 −0.3 −0.6	V
Base−Emitter Saturation Voltage (I_C = −10 mA, I_B = −1.0 mA) (I_C = −50 mA, I_B = −5.0 mA)		$V_{BE(sat)}$	 − −0.65	 −0.8 −0.9	V
SMALL−SIGNAL CHARACTERISTICS					
Magnitude of Small−Signal Current Gain (I_C = −30 mA, V_{CE} = −30 V, f = 100 MHz)	2N3634, 2N3636 2N3635, 2N3637	$\|h_{fe}\|$	 1.5 2.0	 8.0 8.5	−
Small−Signal Current Gain (I_C = −10 mA, V_{CE} = −10 V, f = 1 kHz)	2N3634, 2N3636 2N3635, 2N3637	h_{fe}	 40 80	 160 320	−
Output Capacitance (V_{CB} = −20 V, I_E = 0 A, 100 kHz ≤ f ≤ 1.0 MHz)		C_{obo}	 −	 10	pF
Input Capacitance (V_{EB} = −1.0 V, I_C = 0 A, 100 kHz ≤ f ≤ 1.0 MHz)		C_{ibo}	 −	 75	pF
Noise Figure (V_{CE} = −10 V, I_C = −0.5 mA, R_g = 1 kΩ, f = 100 Hz) (V_{CE} = −10 V, I_C = −0.5 mA, R_g = 1 kΩ, f = 1.0 kHz) (V_{CE} = −10 V, I_C = −0.5 mA, R_g = 1 kΩ, f = 10 kHz)		NF	 − − −	 5.0 3.0 3.0	dB
SWITCHING CHARACTERISTICS					
Delay Time	(Reference Figure 11 in MIL−PRF−19500/357)	t_d	−	100	ns
Rise Time	(Reference Figure 11 in MIL−PRF−19500/357)	t_r	−	100	ns
Storage Time	(Reference Figure 11 in MIL−PRF−19500/357)	t_s	−	500	ns
Fall Time	(Reference Figure 11 in MIL−PRF−19500/357)	t_f	−	150	ns
Turn−Off Time	(Reference Figure 11 in MIL−PRF−19500/357)	t_{off}	−	600	ns

1. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

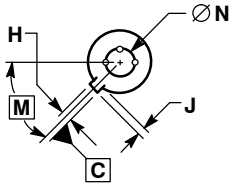
PACKAGE DIMENSIONS

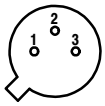
TO−5 3−Lead
CASE 205AA
ISSUE B





DETAIL X





LEAD IDENTIFICATION DETAIL

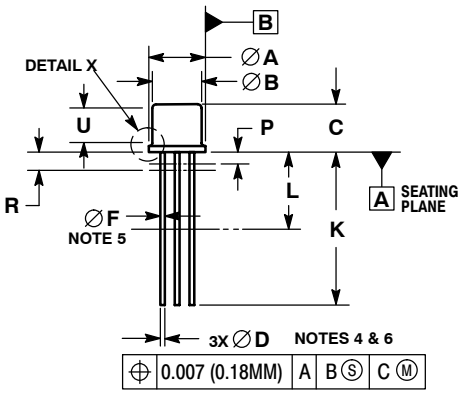
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSION J MEASURED FROM DIAMETER A TO EDGE.
4. LEAD TRUE POSITION TO BE DETERMINED AT THE GUAGE PLANE DEFINED BY DIMENSION R.
5. DIMENSION F APPLIES BETWEEN DIMENSION P AND L.
6. DIMENSION D APPLIES BETWEEN DIMENSION L AND K.
7. BODY CONTOUR OPTIONAL WITHIN ZONE DEFINED BY DIMENSIONS A, B, AND T.
8. DIMENSION B SHALL NOT VARY MORE THAN 0.010 IN ZONE P.

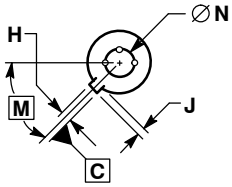
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	8.89	9.40	0.350	0.370
B	8.00	8.51	0.315	0.335
C	6.10	6.60	0.240	0.260
D	0.41	0.53	0.016	0.021
E	0.23	3.18	0.009	0.125
F	0.41	0.48	0.016	0.019
H	0.71	0.86	0.028	0.034
J	0.73	1.02	0.029	0.040
K	38.10	44.45	1.500	1.750
L	6.35	---	0.250	---
M	45 ° BSC		45 ° BSC	
N	5.08 BSC		0.200 BSC	
P	---	1.27	---	0.050
R	1.37 BSC		0.054 BSC	
T	---	0.76	---	0.030
U	2.54	---	0.100	---

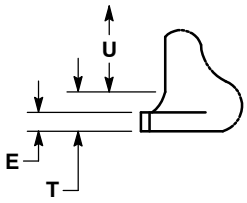
STYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

PACKAGE DIMENSIONS

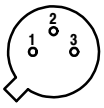
TO−39 3−Lead
CASE 205AB
ISSUE A







DETAIL X



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B	8.00	8.51	0.315	0.335
C	6.10	6.60	0.240	0.260
D	0.41	0.48	0.016	0.019
E	0.23	3.18	0.009	0.125
F	0.41	0.48	0.016	0.019
H	0.71	0.86	0.028	0.034
J	0.73	1.02	0.029	0.040
K	12.70	14.73	0.500	0.580
L	6.35	---	0.250	---
M	45° BSC		45° BSC	
N	5.08 BSC		0.200 BSC	
P	---	1.27	---	0.050
R	1.37 BSC		0.054 BSC	
T	---	0.76	---	0.030
U	2.54	---	0.100	---

STYLE 1:
PIN 1. EMITTER
2. BASE
3. COLLECTOR

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